

T6L24

Source Driver for TFT LCD Panels

The T6L24 is a 240-channel-output source driver for TFT LCD panels.

The T6L24 offers both low power consumption and high integration circuit due to CMOS technology.

Features

- LCD drive outputs : 240 outputs (80 outputs each for R, G and B)
- Power supply voltage : Digital power supply voltage
... 2.7 to 5.5 V
Analog power supply voltage
... Max 5.5 V
- Sampling method : 2 latches
- Data transfer method : Bi directional shift register
- Operating temperature : -20 to 75°C
- Package : Tape carrier package (TCP)
- Switching simultaneous/sequential sampling

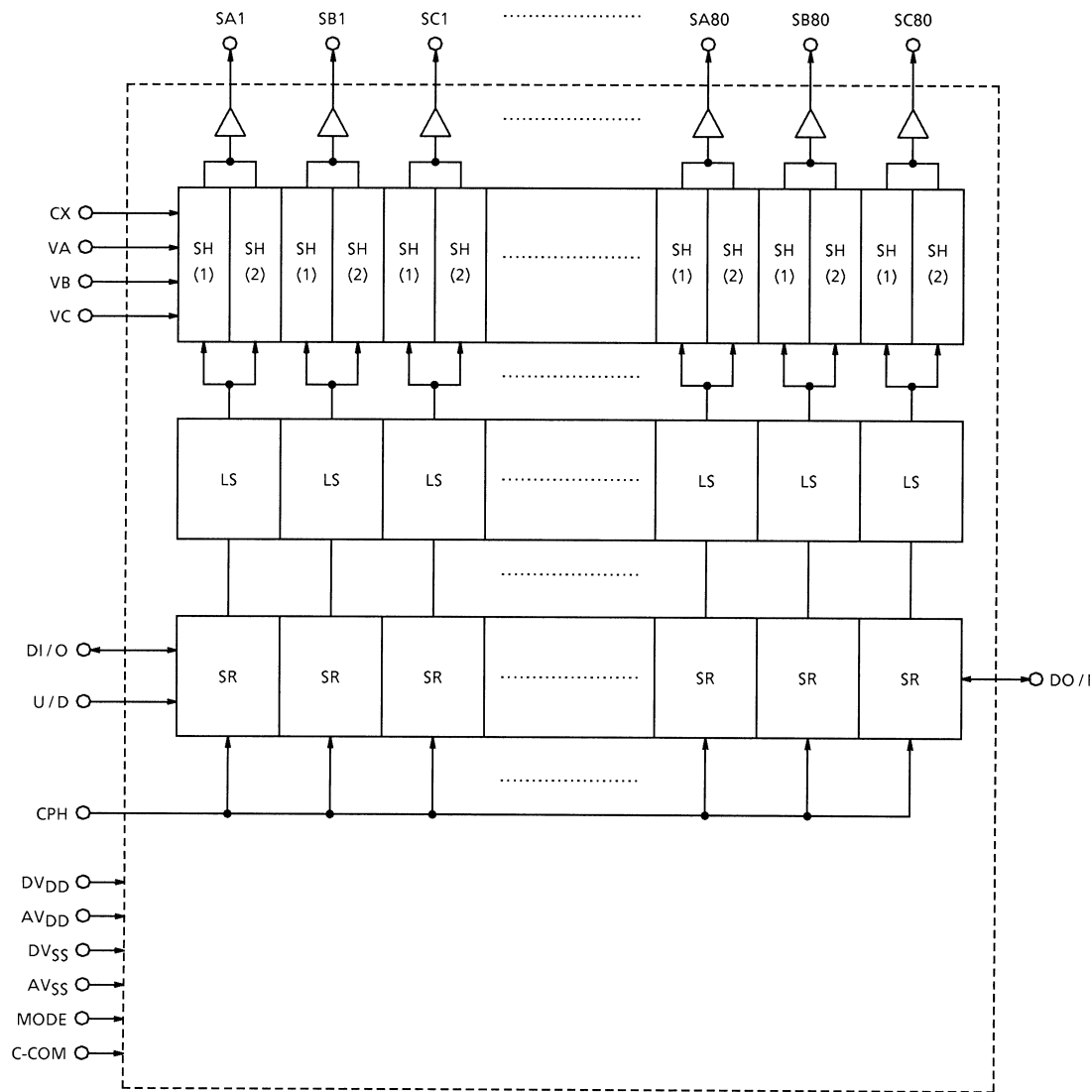
Unit : mm

T6L24	USER AREA PITCH	
	IN	OUT
(SDN, 5ES)	0.85	0.09

Please contact Toshiba or an authorized Toshiba dealer for information on package dimensions.

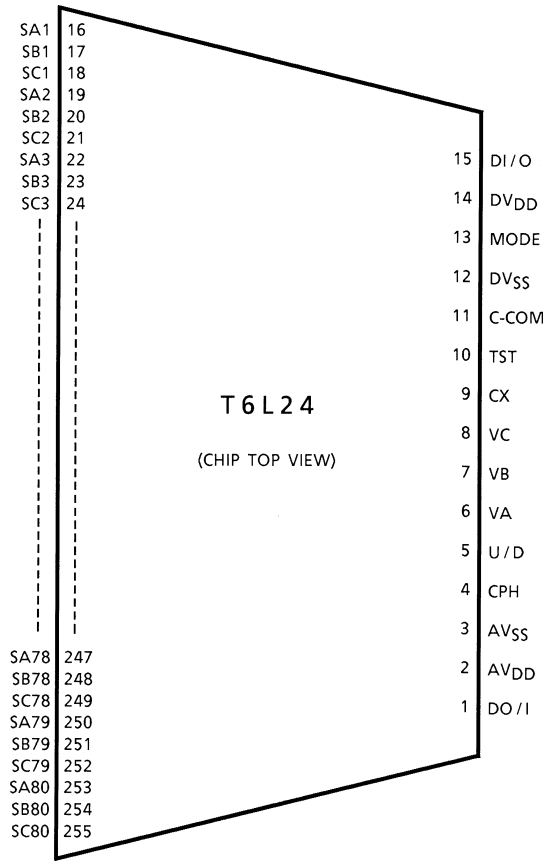
TCP (Tape Carrier Package)

Block Diagram



SR : Shift Register
LS : Level Shifter
SH : Sample-and-Hold Circuit

Pin Assignment



The above diagram shows the device's pin configuration only and does not necessarily correspond to the pad layout on the chip. Please contact Toshiba or our distributor for the latest TCP specification.

Pin Function

Pin Name	I/O	Function									
DI/O DO/I	I/O	<p>Vertical shift data I/O pins These pins are used to input and output shift data. These pins are switched between input and output by setting the U/D pin as shown below:</p> <table border="1"> <tr> <th>U/D</th><th>DI/O</th><th>DO/I</th></tr> <tr> <td>H</td><td>Input</td><td>Output</td></tr> <tr> <td>L</td><td>Output</td><td>Input</td></tr> </table> <p>When set for input</p> <ul style="list-style-type: none"> When MODE = low The data is latched into the internal logic synchronously with the rising edge of CPH. The data is sampling in sequentially, starting at the rise of CPH after three clock period. When MODE = high The data is latched into the internal logic synchronously with the rising edge of CPH. The data is sampling in sequentially, starting at the next rise of CPH. <p>When set for output When two or more T6L24s are cascaded, this pin outputs the data to be fed into the next stage.</p>	U/D	DI/O	DO/I	H	Input	Output	L	Output	Input
U/D	DI/O	DO/I									
H	Input	Output									
L	Output	Input									
U/D	I	<p>Transfer direction select pin This pin specifies the direction of sampling performed by the sample-and-hold circuit.</p> <ul style="list-style-type: none"> When MODE = low When U/D is high, data is sampled in the sequence SA1 → SB1 → SC1 → SA2 → SB2 → ... → SC80 When U / D is low, the sequence is reversed to give SC80 → SB80 → SA80 → SC79 → ... → SA1 When MODE = high When U/D is high, data is sampled in the sequence SA1, SB1, SC1 → SA2, SB2, SC2 → ... → SA80, SB80, SC80 When U/D is low, the sequence is reversed to give SC80, SB80, SA80 → SC79, SB79, SA79 → ... → SC1, SB1, SA1 									
CPH	I	<p>Shift clock input This clock sequentially shift the signals necessary to sample the data that are output to the LCD drive output pins (QA1 to QC80).</p>									
CX	I	<p>Sample-and-hold switching pin. This pin switches between two sample-and-hold circuits.</p>									
MODE	I	<p>Sampling mode setting pin.</p> <ul style="list-style-type: none"> When MODE = high Simultaneously samples three video output signals corresponding to the LCD drive outputs. When MODE = low Sequentially samples the video output signals corresponding to the LCD drive outputs. 									
VA VB VC	I	<p>Analog signal input These pins accept as their input the analog signals that are output to the LCD drive output pins.</p>									
C-COM	I	<p>Sample and hold reference voltage input This is the reference voltage for the sample-and-hold circuit. Apply stable DC voltage to the pin.</p>									
QA1 to QA80 QB1 to QB80 QC1 to QC80	O	<p>LCD drive output pins These pins output one of the analog signal inputs (VA, VB and VC) after it has been sampled and held by the sample-and-hold circuit.</p>									
DV _{DD}	—	Power supply for the device's logic block									
AV _{DD}	—	Power supply for the device's high-voltage block									
DV _{SS}	—	Digital GND for the device									
AV _{SS}	—	Analog GND for the device									
TST	—	<p>Test pin Use the pin as required.</p>									

Device Operation

(1) Analog signal sampling

Data transfer begins with the assertion of DI/O (U/D = high) or DO/I (U/D = low).

<Simultaneous sampling>

- **When MODE = high, U/D = high**

A high on DI/O is latched into the internal logic synchronously with the rising edge of CPH, and the analog signal to be output to (SA1, SB1, SC1) is sampled at next rising edge of CPH. In this way, all analog signals are sampled of each three channel sequentially at the rising edge of CPH and so on, and the analog signals are output to (SA2, SB2, SC2), (SA3, SB3, SC3) and so on.

After the device finishes sampling the data for (SA80, SB80, SC80), it automatically enters standby state. Unless DI/O is asserted again, no data is sampled, irrespective of whether CPH are input to the device.

- **When MODE = high, U/D = low**

A high on DO/I is latched into the internal logic synchronously with the rising edge of CPH, and the analog signal to be output to (SA80, SB80, SC80) is sampled at next rising edge of CPH. In this way, all analog signals are sampled of each three channel sequentially at the rising edge of CPH and so on, and the analog signals are output to (SA79, SB79, SC79), (SA78, SB78, SC78) and so on.

After the device finishes sampling the data for (SA1, SB1, SC1), it automatically enters standby state. Unless DO/I is asserted again, no data is sampled, irrespective of whether CPH are input to the device.

<Sequential sampling>

- **When MODE = low, U/D = high**

A high on DI/O is latched into the internal logic synchronously with the rising edge of CPH, and the analog signal to be output to SA1 is sampled at the rising edge of CPH after three clock period. In this way, all analog signals are sampled sequentially at the rising edge of CPH and so on, and the analog signals are output to SB1, SC1, SA2, SB2, SC2, SA3, SB3, SC3 and so on.

After the device finishes sampling the data for SC80, it automatically enters standby state. Unless DI/O is asserted again, no data is sampled, irrespective of whether CPH are input to the device.

- **When MODE = low, U/D = low**

A high on DO/I is latched into the internal logic synchronously with the rising edge of CPH, and the analog signal to be output to SC80 is sampled at the rising edge of CPH after three clock period. In this way, all analog signals are sampled sequentially at the rising edge of CPH and so on, and the analog signals are output to SB80, SA80, SC79, SB79, SA79, SC78, SB78, SA78 and so on.

After the device finishes sampling the data for SA1, it automatically enters standby state. Unless DO/I is asserted again, no data is sampled, irrespective of whether CPH are input to the device.

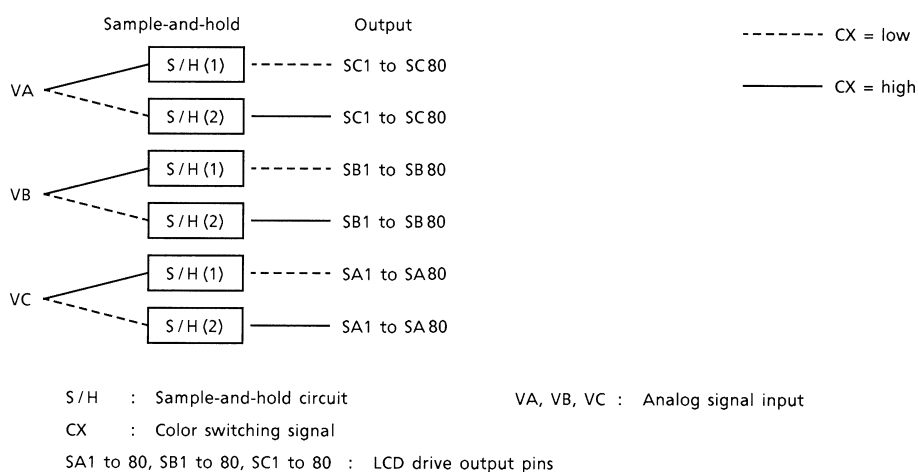
(2) LCD drive output

- The T6L24 has two sample-and-hold circuits called Sample-And-Hold (1) and (2). These two circuits alternate between serving as the output and the sample-and-hold. Which circuit fulfils which function is determined by the setting of the CX pin.

CX	Output	Sample-and-Hold
L	Sample-and-hold circuit (1)	Sample-and-hold circuit (2)
H	Sample-and-hold circuit (2)	Sample-and-hold circuit (1)

- The analog signal inputs VA, VB and VC are output as follows: VA is sent to the LCD driver output pins SC1 to SC80, VB is sent to output pins SB1 to SB80, and VC is sent to output pins SA1 to SA80. The analog signal inputs will be sent to LCD driver output pins by the setting of the CX pin as shown below:

Note: The CX pin setting must not be altered while the device is sampling data.



(3) Vertical shift data output

• When MODE = high

The output DO/I (U/D = high) or DI/O (U/D = low) is driven high for one clock period synchronously with the rising CPH, one clock period before the data (which is to be output to (SA80, SB80, SC80) or (SA1, SB1, SC1)) is latched into the shift register.

• When MODE = low

The output DO/I (U/D = high) or DI/O (U/D = low) is driven high for one clock period synchronously with the rising CPH, one clock period before the data (which is to be output to SA80 or SC1) is latched into the shift register.

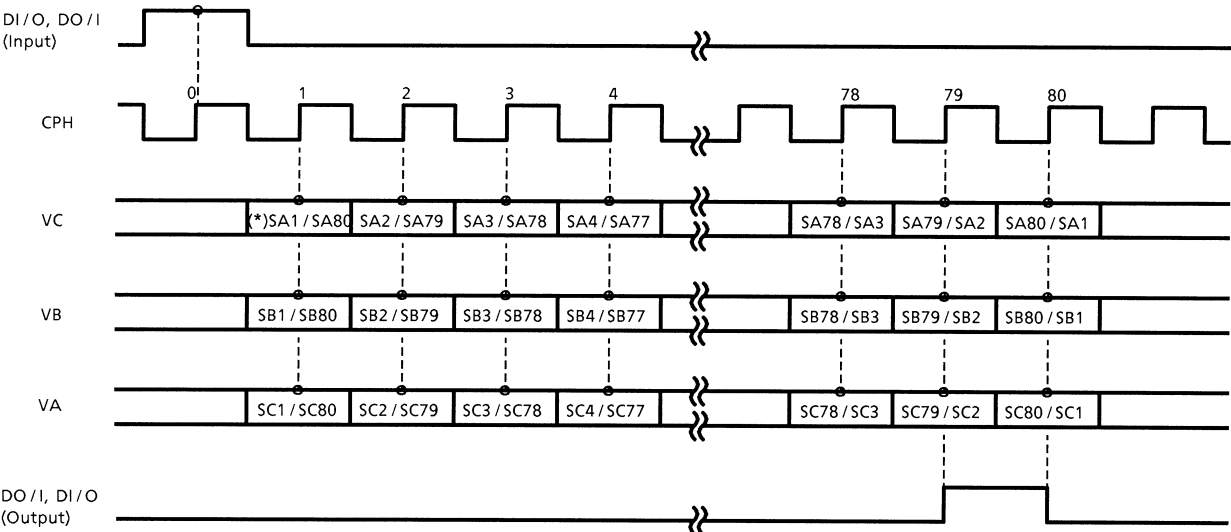
When using two or more of these devices to drive a large screen, connect the vertical shift data output from the first stage of the LCD driver directly to the vertical shift data input at the next stage. In this way, the device's LCD drive output pin can easily be expanded as necessary.

(4) Sample-and-hold reference voltage (C-COM)

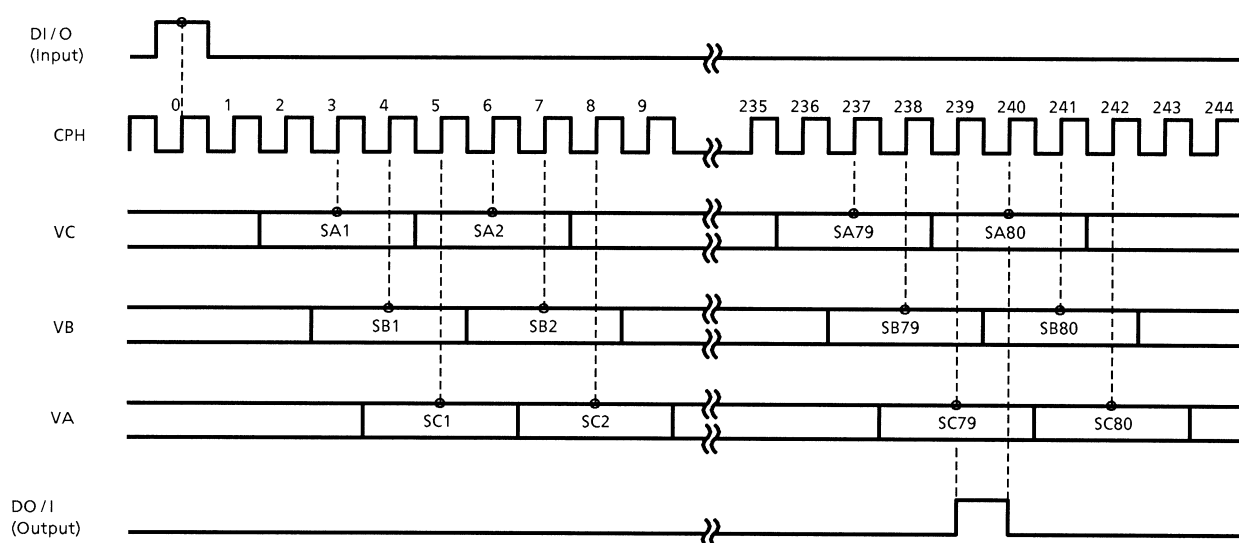
The device's sample-and-hold circuits are configured using the internal capacitors. The C-COM pin is used to supply the reference voltage for these circuits. Apply stable DC voltage to the pin.

Timing Diagram

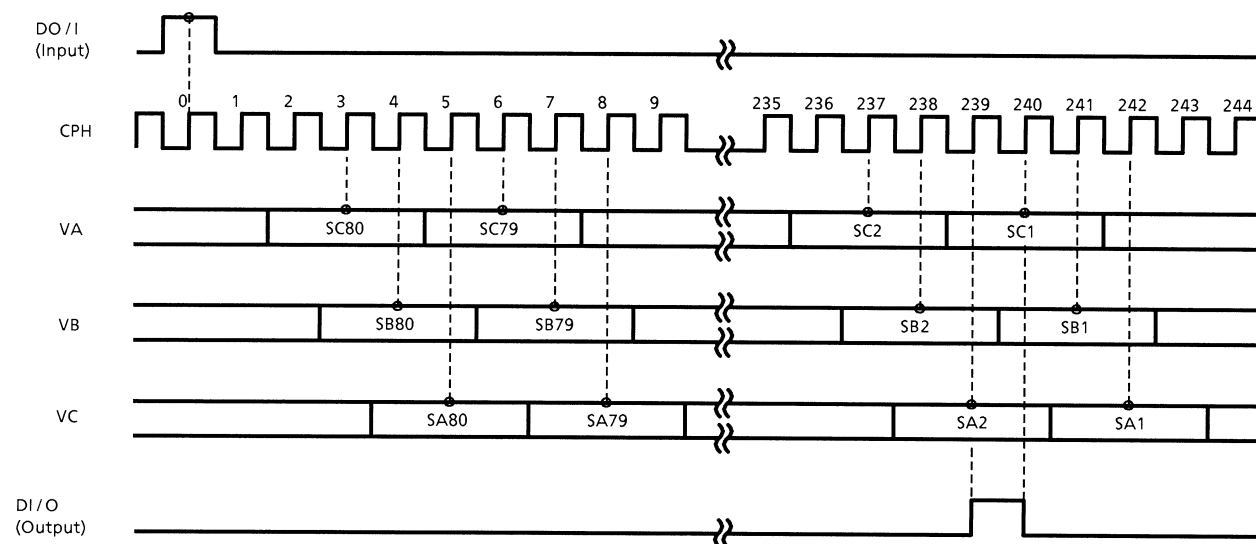
- Simultaneous sampling (MODE = high)



- Sequential sampling (MODE = low, U/D = high)



- Sequential sampling (MODE = low, U/D = low)



Absolute Maximum Ratings ($AV_{SS} = DV_{SS} = 0\text{ V}$)

Parameter	Symbol	Rating	Unit	Relevant Pin
Supply Voltage (1)	DV_{DD}	-0.3 to 6.5	V	—
Supply Voltage (2)	AV_{DD}	-0.3 to 6.5	V	—
Digital Input Voltage	V_{IN}	-0.3 to $DV_{DD} + 0.3$	V	(Note 1)
Reference Analog Voltage	V_{ID}	-0.3 to $AV_{DD} + 0.3$	V	(Note 2)
Storage Temperature	T_{stg}	-55 to 125	°C	—

Recommended Operating Conditions ($AV_{SS} = DV_{SS} = 0\text{ V}$)

Parameter	Symbol	Rating	Unit	Relevant Pin
Supply Voltage (1)	DV_{DD}	2.7 to 5.5	V	—
Supply Voltage (2)	AV_{DD}	DV_{DD} to 5.5	V	—
Reference Analog Voltage	V_{ID}	0.2 to $AV_{DD} - 0.2$	V	(Note 2)
Operating Temperature	T_{OP}	-20 to 75	°C	—
Operating Frequency	MODE = high	f_{CLK}	0.5 to 15	—
	MODE = low	f_{CLK}	0.5 to 30	—
Output Load Capacitance	C_L	50 (max)	pF/PIN	—
Input Capacitance	C_{IN}	10 (max)	pF	—

Electrical Characteristics

DC Characteristics

($DV_{DD} = 3.0 \pm 0.3\text{ V}$, $AV_{DD} = 5.0 \pm 0.5\text{ V}$, $AV_{SS} = DV_{SS} = 0\text{ V}$, $T_a = -20\text{ to }75^\circ\text{C}$)

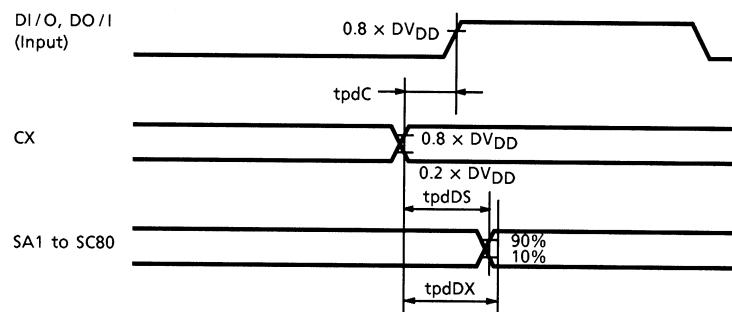
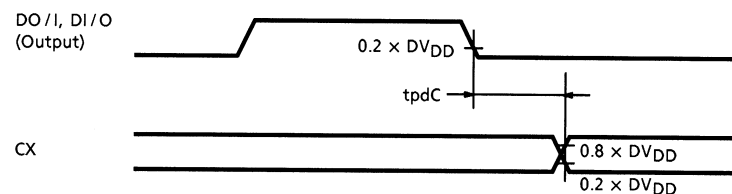
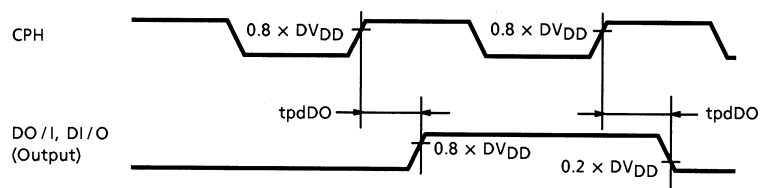
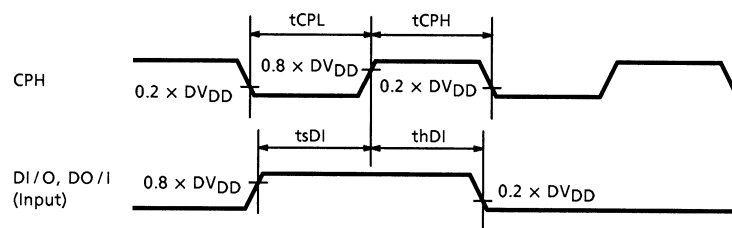
Parameter	Symbol	Test Circuit	Test Conditions	Min	Typ.	Max	Unit	Relevant Pin
Input Voltage	Low Level	V_{IL}	—	0	—	$0.2 \times DV_{DD}$	V	(Note 1)
	High Level	V_{IH}	—	$0.8 \times DV_{DD}$	—	DV_{DD}		
Output Voltage	Low Level	V_{OL}	$I_{OL} = 40\text{ }\mu\text{A}$	0	—	0.3	V	DI/O, DO/I
	High Level	V_{OH}	$I_{OL} = -40\text{ }\mu\text{A}$	$V_{DD} - 0.3\text{ V}$	—	DV_{DD}		
Output Offset Voltage	V_{OFF}	—	—	-20	—	—	mV	SA1 to SC80
Input Current	I_{IN}	—	—	-1	—	—	μA	(Note 1)
Current Consumption (1)	DI_{DD}	—	—	—	—	—	mA	DV_{DD}
Current Consumption (2)	AI_{DD}	—	—	—	—	—	mA	AV_{DD}

Note 1: All input pins except the analog signal input pins (VA, VB, VC)

Note 2: Analog signal input pins (VA, VB, VC)

AC Characteristics**($DV_{DD} = 3.0 \pm 0.3$ V, $AV_{DD} = 5.0 \pm 0.5$ V, $AV_{SS} = DV_{SS} = 0$ V, $T_a = -20$ to 75°C)**

Parameter	Symbol	Test Circuit	Test Conditions	Min	Typ.	Max	Unit
Operating Frequency	f _{CPH} (1 / t _{CPH})	—	MODE = low	0.5	—	30	MHz
			MODE = high	0.5	—	15	
CPH Pulse Width H	t _{CWH}	—	—	12	—	—	ns
CPH Pulse Width L	t _{CWL}	—	—	12	—	—	ns
Data Set-up Time	t _{DSU}	—	—	5	—	—	ns
Data Hold Time	t _{DHD}	—	—	5	—	—	ns
CX Set-up Time	t _{pdC}	—	—	5	—	—	CPH period
Output Delay Time 1	t _{pdDO}	—	C _L = 30 pF	—	—	16	ns
Output Delay Time 2	t _{pdDS}	—	C _L = 50 pF Target output voltage (90%, 10%)	—	—	8	μs
Output Delay Time 3	t _{pdDX}	—	C _L = 50 pF, Target output voltage	—	—	15	μs



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